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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Applicant:

Brian Taggart et al.

Serial No.: 10/807,830

Filed: March 24, 2004

For: Lower Profile Flexible Substrate
Package for Electronic Components

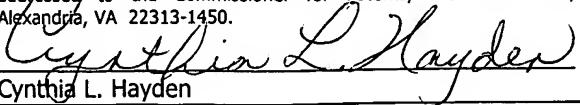
§ Art Unit: 2825
§ Examiner: Calvin Lee
§ Docket: ITL.1119US
§ P18791
§ Assignee: Intel Corporation

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

REPLY TO PAPER NO. 2

Sir:

In response to the office action mailed January 4, 2005, please amend the above-referenced patent application as follows:

Date of Deposit: <u>March 7, 2005</u>
I hereby certify under 37 CFR 1.8(a) that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage on the date indicated above and is addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Cynthia L. Hayden